

Subject: RoHS EXEMPTIONS – Addendum to EU Declaration

Table 1. Residual Current Circuit Breakers (RCCBs)	
Substance/Substance Group Name: Lead and its compounds	
Electronic component/s mounted inside trip units of F202-204 series Metal component/s mounted inside trip units of F202-204 series Metal component/s mounted inside trip units of F400 series Electronic component/s mounted inside trip units of Basic M-BMF series Metal component/s mounted inside trip units of Basic M-BMF series Electronic component/s mounted inside trip units of FMF series Electronic component/s mounted inside trip units of FH200 series Metal component/s mounted inside trip units of FH200 series Electronic component/s mounted inside trip units of FX202-FX204 Metal component/s mounted inside trip units of FX202-FX204	
Exemption	6a - Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35% lead by weight
Exemption	7a - Lead in high melting temperature type solders (i.e. lead based alloys containing 85 % by weight or more lead) 7(c)-I - Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

Table 2. Residual Current Devices (RCDs)	
Substance/Substance Group Name: Lead and its compounds	
Electronic component/s mounted inside trip units of DDA 200 series Metal component/s mounted inside trip units of DDA 200 series Electronic component/s mounted inside trip units of DDA 800 series Metal component/s mounted inside trip units of DDA 800 series	
Exemption	6a - Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35% lead by weight
Exemption	7a - Lead in high melting temperature type solders (i.e. lead based alloys containing 85 % by weight or more lead) 7(c)-I - Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

Table 3. Residual Current Circuit Breaker with Overcurrent protection (RCBO)	
Substance/Substance Group Name: Lead and its compounds	
Metal component/s mounted inside trip units of DS201 series Electronic component/s mounted inside trip units of DS201 series Metal component/s mounted inside trip units of DS202 series Electronic component/s mounted inside trip units of DS202 series Metal component/s mounted inside trip units of DS203NC series Electronic component/s mounted inside trip units of DS203NC series Metal component/s mounted inside trip units of DS301 series Electronic component/s mounted inside trip units of DSE201 series Metal component/s mounted inside trip units of DSX301C Metal component/s mounted inside trip units of DSX203NC series Electronic component/s mounted inside trip units of DSX203NC series	
Exemption	6a - Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35% lead by weight
Exemption	7a - Lead in high melting temperature type solders (i.e. leadbased alloys containing 85 % by weight or more lead) 7(c)-I - Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

Table 4. Arc Fault Detection Device integrated with MCB	
Substance/Substance Group Name: Lead and its compounds	
Metal component/s mounted inside trip units of S-ARC1 Metal component/s mounted inside trip units of SX-ARC1	
Exemption	6c - Copper alloys containing up to 4 % lead by weight

Table 5. Energy Meters EV1 and EV3 012-100	
Substance/Substance Group Name: Lead and its compounds	
Metal component/s mounted inside of Meter	
Exemption	6c – Copper alloys containing up to 4 % lead by weight

Table 6. Busbars & DIN-Rail Accessories	
Substance/Substance Group Name: Lead and its compounds	
Metal component/s mounted inside trip units of S2C series	
Exemption	6c – Copper alloys containing up to 4 % lead by weight

Table 7. Accessories for RCDs	
Substance/Substance Group Name: Lead and its compounds	
Metal component/s mounted inside trip units of F2C-A2 series	
Exemption	6c – Copper alloys containing up to 4 % lead by weight

Table 8. Modular sockets	
Substance/Substance Group Name: Lead and its compounds	
Metal component/s mounted inside trip units of M1174 series	
Exemption	6c – Copper alloys containing up to 4 % lead by weight

Table 9. Modular Transformer	
Substance/Substance Group Name: Lead and its compounds	
Metal component/s mounted inside trip units of TS-C; TM; TS series	
Exemption	6a – Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35% lead by weight

Table 10. Current Transformer	
Substance/Substance Group Name: Lead and its compounds	
Metal component/s mounted inside trip units of CT series	
Exemption	6c – Copper alloys containing up to 4 % lead by weight

Table 11. Miniature Circuit Breaker Accessories	
Substance/Substance Group Name: Lead and its compounds	
Metal component/s mounted inside trip units of S2-Hxx FS series	
Exemption	6a – Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35% lead by weight
Exemption	6c – Copper alloys containing up to 4 % lead by weight

Table 12. ABB Vynckier Autoreclosing device RCCB	
Substance/Substance Group Name: Lead and its compounds	
Metal component/s mounted inside trip units of TeleREC2 series	
Exemption	6a – Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35% lead by weight

Table 13. Digital Voltmeter/Digital Ammeter VLMD - AMTD	
Substance/Substance Group Name: Lead and its compounds	
Metal component/s mounted inside of Measuring instruments	
Exemption	6c – Copper alloys containing up to 4 % lead by weight

Table 14. Fuse disconnectors	
Substance/Substance Group Name: Lead and its compounds	
Electronic component/s mounted inside of E90/s	
Exemption	7(c)-I - Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

Table 15. Miniature circuit breakers for overcurrent protection	
Substance/Substance Group Name: Lead and its compounds	
Metal component/s mounted inside trip units of AC22	
Exemption	6a – Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35% lead by weight

Table 16. Current Operated Circuit Breakers with Integral Overcurrent	
Substance/Substance Group Name: Lead and its compounds	
Metal component/s mounted inside trip units of DC22.	
Exemption	6a – Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35% lead by weight

Table 17. Front panel residual current relays	
Substance/Substance Group Name: Lead and its compounds	
Metal component/s mounted inside trip units of ELR series	
Exemption	8b - Cadmium and its compounds in electrical contacts

Table 18. Connectivity module INS-USB, INS-LTE, INS-Lora, INS-HUB	
Substance/Substance Group Name: Lead and its compounds	
Component/s inside products INS USB, INS-LTE, INS-Lora, INS-HUB	
Exemption	6c – Copper alloys containing up to 4 % lead by weight 7a - Lead in high melting temperature type solders (i.e. leadbased alloys containing 85 % by weight or more lead) 7(c)-I - Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

Table 19. Autoreclosing RCCB with Autotest F-ARI Type B	
Substance/Substance Group Name: Lead and its compounds	
Metal component/s	
Electronic component/s mounted inside	
Exemption	6(c) – Copper alloys containing up to 4 % lead by weight
Exemption	7(a) - Lead in high melting temperature type solders (i.e. leadbased alloys containing 85 % by weight or more lead)
Exemption	7(c)-I - Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

Table 20. RCCB Autotest F-ATI Type B	
Substance/Substance Group Name: Lead and its compounds	
Metal component/s	
Electronic component/s mounted inside	
Exemption	6(c) – Copper alloys containing up to 4 % lead by weight
Exemption	7(a) - Lead in high melting temperature type solders (i.e. leadbased alloys containing 85 % by weight or more lead)
Exemption	7(c)-I - Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

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